

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 4.294192**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.006856	1000000	1596.57519531		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	1.296750	975000	301977.625		
		Iron (Fe)	7439-89-6	0.031920	24000	7433.296875		
		Phosphorus (P)	7723-14-0	0.000399	300	92.9162063599		
		Zinc (Zn)	7440-66-6	0.000931	700	216.804473877		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>1.330000</b>	<b>1000000</b>	<b>309720.6875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.043454	1000000	10119.1396484		
		<b>External Plating Total:</b>				<b>0.043454</b>	<b>1000000</b>	<b>10119.1396484</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.010640	1000000	2477.76538086		
<b>Internal Plating Total:</b>				<b>0.010640</b>	<b>1000000</b>	<b>2477.76538086</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001682	750000	391.691864014		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000561	250000	130.641586304		
<b>Die Attach Total:</b>				<b>0.002243</b>	<b>1000000</b>	<b>522.333496094</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.391500	135000	91169.65625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	2.494000	860000	580784.5		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.014500	5000	3376.65380859		
		<b>Encapsulation Total:</b>				<b>2.900000</b>	<b>1000000</b>	<b>675330.8125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000999	1000000	232.639831543		
					<b>TOTAL MASS (g) :</b>	<b>4.294192</b>		